

*A Symposium Update from
Chapter Vice-President, Dmitry Marchenko*



Dear Members, Friends and Colleagues!

On behalf of the iMAPS New England Chapter Executive Committee, I hope 2017 started out great for all of you. We were extremely grateful for your support in 2016, which ended on a high note with our, now traditional, Winter Holiday Social.

We are working hard to maintain the high standards of technical relevance set in past years. Dr. Parshant Kumar from Draper, together with his Session Chairs is working tirelessly to bring an all-new exciting Technical Program to our 2017 Annual Symposium and Expo on May 2, 2017.

We will have the latest advances in RF and Microwave Packaging from technical expertise powerhouses like Skyworks, CST and BAE Systems. Our colleagues from Sensata and Draper will be sharing their findings in the areas of MEMS and Nano-Packaging, while our Thermal Management session is back to present the challenges of packaging handheld, mobile and medical devices. More new information about the latest work in Printed Electronics will be shared by engineers from Optomec, Dow Chemical and Voxel8. You've shown consistent interest in Medical Device Packaging and our colleagues from MIT, Draper and Brown University will be reporting on their latest innovations as well.

I know you will find this program compelling enough to attend the Symposium and will be delighted to see you there. Dr. Kumar and his team are still accepting Abstracts for the event, so act soon.

We are always looking for new volunteers so, if you are interested in helping to organize the Symposium or Technical Meetings, please contact our President, Jon Medernach or me.

I'm very pleased by your continued commitment,

Dmitry Marchenko, Vice-President (dmitry.marchenko@live.com)

iMAPS New England Chapter